RC4136, RM4136, RV4136 QUAD GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

The RM4136 and RV4136 are obsolete and are no longer supplied.

SLOS072A - MARCH 1978 - REVISED JANUARY 2002

- Continuous Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- Low Power Consumption
- No Latch-Up
- Unity-Gain Bandwidth . . . 3 MHz Typ
- Gain and Phase Match Between Amplifiers
- Designed To Be Interchangeable With Raytheon RC4136, RM4136, and RV4136
- Low Noise . . . 8 nV√Hz Typ at 1 kHz

description

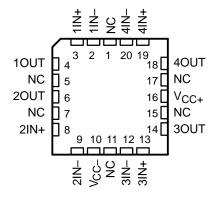
The RC4136, RM4136, and RV4136 are quad general-purpose operational amplifiers, with each amplifier electrically similar to the μ A741, except that offset null capability is not provided.

The high common-mode input voltage range and the absence of latch-up make these amplifiers ideal for voltage-follower applications. The devices are short-circuit protected and the internal frequency compensation ensures stability without external components.

The RC4136 is characterized for operation from 0°C to 70°C, the RM4136 is characterized for operation over the full military temperature range of -55°C to 125°C, and the RV4136 is characterized for operation from -40°C to 85°C.

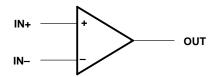
RM4136...J OR W PACKAGE ALL OTHERS ... D OR N PACKAGE (TOP VIEW) 14 🛮 4IN-1IN-1IN+ [13 ¶ 4IN+ 10UT [12 40UT 3 20UT [11 V_{CC+} 5 10 ¶ 3OUT 2IN- [9 3IN+ 8 3IN− V_{CC}

RM4136 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

symbol (each amplifier)



AVAILABLE OPTIONS

	VIOMAX	PACKAGE									
TA	AT 25°C	SMALL OUTLINE (D)	CHIP CARRIER (FK)	CERAMIC DIP (J)	PLASTIC DIP (N)	FLAT (W)					
0°C to 70°C	6 mV	RC4136D	_	_	RC4136N						
-40°C to 85°C	6 mV	RV4136D	_	_	RV4136N	_					
–55°C to 125°C	4 mV	_	RM4136FK	RM4136J	_	RM4136W					

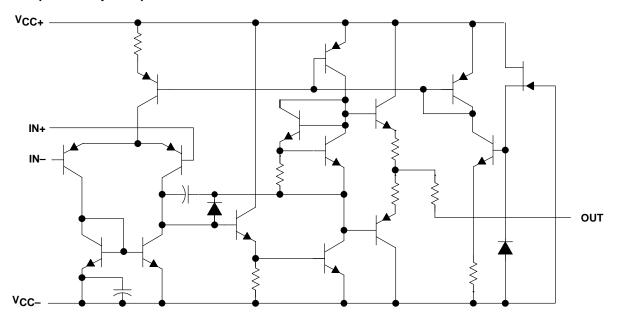
The D packages are available taped and reeled. Add the suffix R to the device type (e.g., RC4136DR).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



schematic (each amplifier)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V _{CC+} RC4136 and RV4136	18 V
V _{CC+} RM4136	22 V
V _{CC} _ RC4136 and RV4136	
V _{CC} _ RM4136	
Differential input voltage, V _{ID} (see Note 2)	$\dots \dots \pm 30 \ V$
Input voltage, V _I (any input) (see Notes 1 and 3)	±15 V
Duration of output short circuit to ground, one amplifier at a time (see Note 4)	Unlimited
Continuous total dissipation	One Displaction Detical Table
Continuous total dissipation	See Dissipation Rating Table
Package thermal impedance, θ_{JA} (see Note 5): D package	
Package thermal impedance, θ_{JA} (see Note 5): D package	
Package thermal impedance, θ_{JA} (see Note 5): D package	86°C/W
Package thermal impedance, θ_{JA} (see Note 5): D package N package	
Package thermal impedance, θ_{JA} (see Note 5): D package	
Package thermal impedance, θ_{JA} (see Note 5): D package	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between VCC+ and VCC-.

- 2. Differential voltages are at IN+ with respect to IN-.
- 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
- 4. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
- 5. The package thermal impedance is calculated in accordance with JESD 51-7.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR	DERATE ABOVE T _A	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
FK	800 mW	11.0 mW/°C	77°C	800 mW	715 mW	275 mW
J	800 mW	11.0 mW/°C	77°C	800 mW	715 mW	275 mW
W	800 mW	8.0 mW/°C	50°C	640 mW	520 mW	200 mW



SLOS072A - MARCH 1978 - REVISED JANUARY 2002

recommended operating conditions

		MIN	MAX	UNIT
V _{CC+}	Supply voltage	5	15	V
VCC-	Supply voltage	-5	-15	V

electrical characteristics at specified free-air temperature, $V_{CC+} = 15 \text{ V}$, $V_{CC-} = -15 \text{ V}$

	DADAMETED	TEAT AGNIDITIO	F	RC4136	6	RM4136			RV4136			UNIT		
ľ	PARAMETER	TEST CONDITIO	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNII		
	Input offset		25°C		0.5	6		0.5	4		0.5	6		
V_{IL}	voltage	V _O = 0	Full range			7.5			6			7.5	mV	
	-		25°C		5	200		5	150		5	200		
I _{IO}	Input offset	V _O = 0	Full			200	_		130			200	nA	
.10	current	1,0 - 0	range			300			500			500	""	
			25°C		140	500		140	400		140	500		
IIB	Input bias current	VO = 0	Full range			800			1500			1500	nA	
Vi	Input voltage range		25°C	±12	±14		±12	±14		±12	±14		V	
	Maximum naak	$R_L = 10 \text{ k}\Omega$	25°C	±12	±14		±12	±14		±12	±14			
Vом	Maximum peak output voltage	$R_L = 2 k\Omega$	25°C	±10	±13		±10	±13		±10	±13		V	
V OIVI	swing	$R_L \ge 2 k\Omega$	Full range	±10			±10			±10				
	Large-signal	V- 140 V	25°C	20	300		50	350		20	300			
AVD	differential voltage amplification	$V_O = \pm 10 \text{ V},$ $R_L \ge 2 \text{ k}\Omega$	Full range	15			25			15			V/mV	
B ₁	Unity-gain bandwidth		25°C		3			3.5			3		MHz	
rį	Input resistance		25°C	0.3*	5		0.3*	5		0.3*	5		MΩ	
CMRR	Common-mode rejection ratio	$V_O = 0$, $R_S = 50 \Omega$	25°C	70	90		70	90		70	90		dB	
kSVS	Supply-voltage sensitivity (ΔV _{IO} /ΔV _{CC})	$V_{CC} = \pm 9 \text{ V to } \pm 15 \text{ V},$ $V_{O} = 0$	25°C		30	150		30	150		30	150	μV/V	
Vn	Equivalent input noise voltage (closed loop)	$A_{VD} = 100$, BW = 1 Hz, f = 1 kHz, $R_{S} = 100 \Omega$	25°C		8			8			8		nV√Hz	
			25°C		5	11.3		5	11.3		5	11.3		
ICC	Supply current (all four amplifiers)	$V_O = 0$, No load	MIN T _A		6	13.7		6	13.3		6	13.7	mA	
			MAX T _A		4.5	10		4.5	10		4.5	10	<u> </u>	
	Total power		25°C		150	340		150	340		150	340		
P_{D}	dissipation	V _O = 0, No load	MIN T _A		180	400		180	400		180	400	mW	
	(all four amplifiers)		MAX T _A		135	300		135	300		135	300		
	Crosstalk attenuation (VO1/VO2)	$A_{VD} = 100,$ f = 10 kHz, $R_{S} = 1 \text{ k}\Omega$	25°C		105			105			105		dB	

^{*} This parameter is not production tested.

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range is 0°C to 70°C for RC4136, –55°C to 125°C for RM4136, and –40°C to 85°C for RV4136. Minimum T_A is 0°C for RC4136, –55°C for RM4136, and –40°C for RV4136. Maximum T_A is 70°C for RC4136, 125°C for RM4136, and 85°C for RV4136.



RC4136, RM4136, RV4136 QUAD GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS072A - MARCH 1978 - REVISED JANUARY 2002

The RM4136 and RV4136 are obsolete and are no longer supplied.

operating characteristics, V_{CC+} = 15 V, V_{CC-} = -15 V, T_A = 25°C

	PARAMETER	TE	TYP	UNIT	
t _r	Rise time	$V_I = 20 \text{ mV},$	$C_L = 100 \text{ pF}, R_L = 2 \text{ k}\Omega$	0.13	μs
	Overshoot factor	$V_I = 20 \text{ mV},$	$C_L = 100 \text{ pF}, R_L = 2 \text{ k}\Omega$	5	%
SR	Slew rate at unity gain	V _I = 10 V,	$C_L = 100 \text{ pF}, R_L = 2 \text{ k}\Omega$	1.7	V/μs



PACKAGE OPTION ADDENDUM

23-Apr-2013

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
RC4136D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
RC4136DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
RC4136N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	RC4136N	Samples
RC4136NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	RC4136N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have not been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

power.ti.com

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

Power Mgmt

OMAP Applications Processors www.ti.com/omap **TI E2E Community** e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity